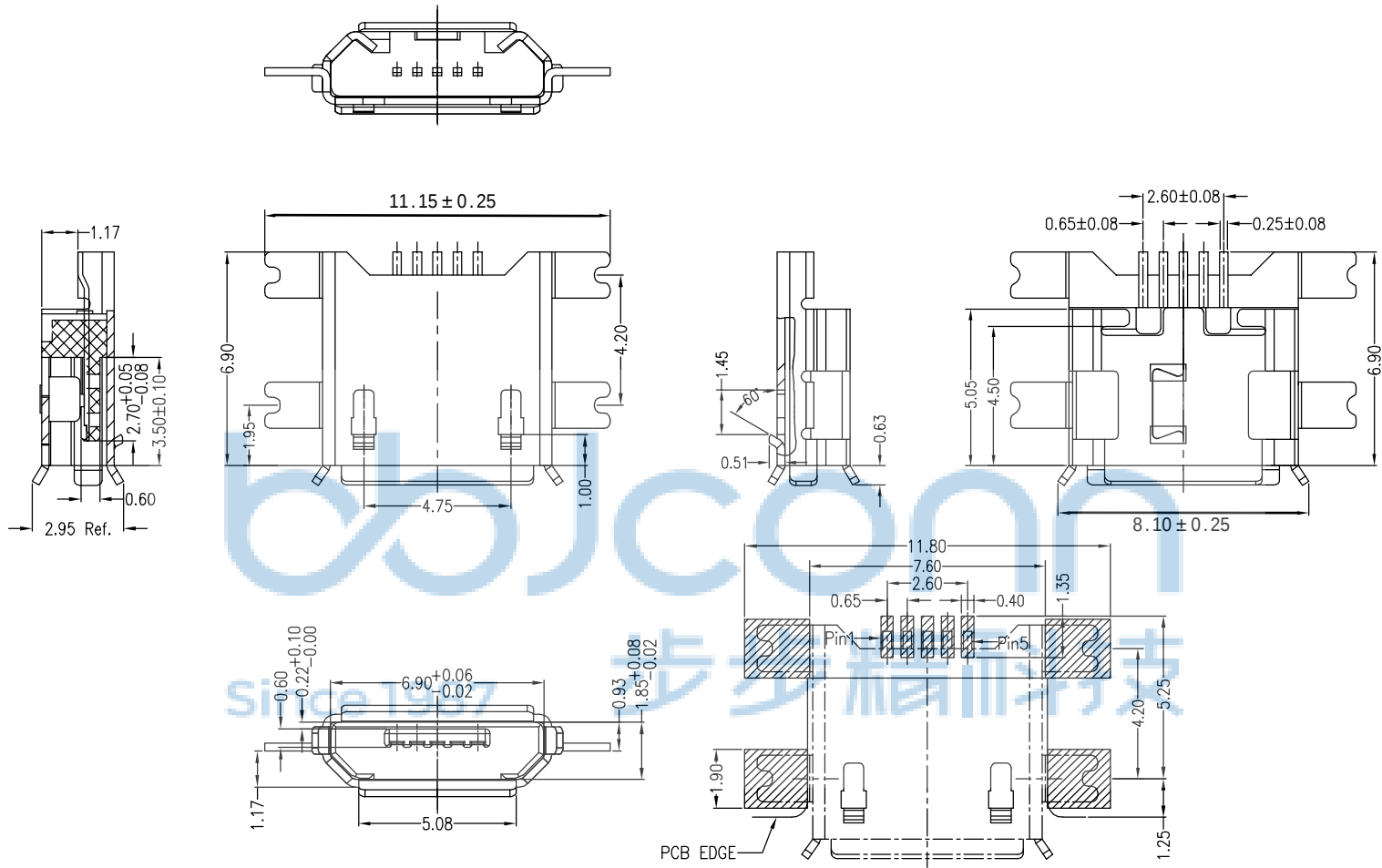


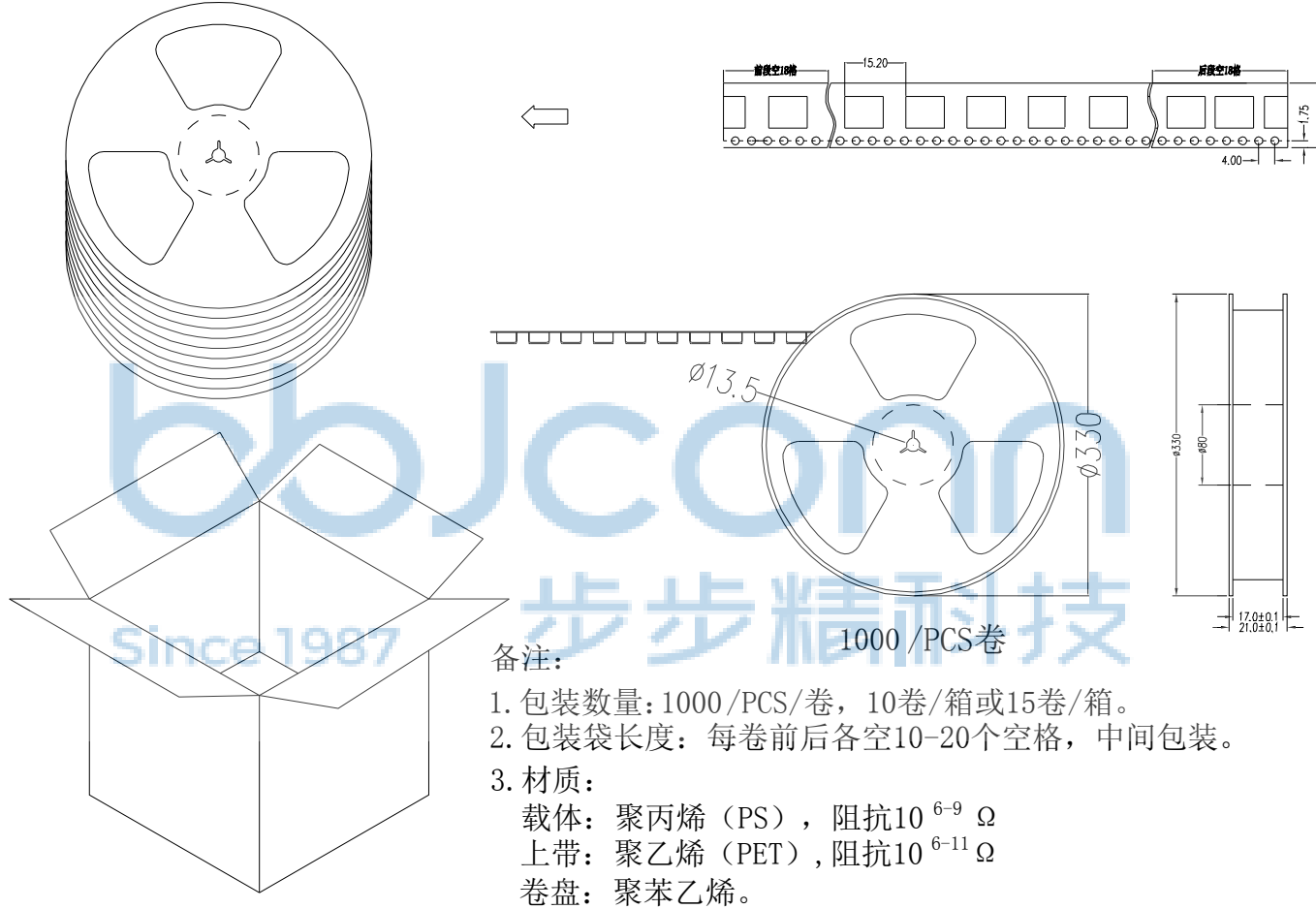


RECOMMENDED PCB LAYOUT

- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f,UL94v-0
 - Contact: copper alloy,t=0.15mm
 - Shell: copper alloy,t=0.25mm
 - Specification:
 - Current rating: 1 A Max.
 - Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - Contact resistance: 30 MΩ Max.
 - Insulation resistance: 100 MΩ Min.
 - Total mating force: 3.57 Kgf Max.
 - Total unmating force: 1.0 Kgf Min.
 - Temperature range: -30°C~80°C



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Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.				NAME: MICRO-5P L=6.90 沉板1.17 四脚贴片 卷边 铜壳 雾锡			
PDWG.NO: 0113-1				PJ. NO.: MC.01.71-11-1002			
DR. SGF				SIZE: A4 DRW NO.:			
				FINISH: SEE NOTES MAT'L.: SEE NOTES			
				SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1			



- 备注:
1. 包装数量: 1000 /PCS /卷, 10卷 /箱或15卷 /箱。
 2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
 3. 材质:
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$
卷盘: 聚苯乙烯。

纸箱规格: 345*345*23MM
纸箱规格: 345*345*35MM



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X*: ±3" .X*: ±2" .XX*: ±1"		NAME: MICRO-5P L=6.90 沉板1.17 四脚贴片 卷边 铜壳 雾锡			
APPD.		JM_Zheng 23/05'02		PJ. NO.: MC.01.71-11-1002			
CHKD.		LYX 23/05'02		SIZE: A4 DRW NO.:			
PDWG.NO: 0113-1		DR. SGF 23/05'02		FINISH: SEE NOTES MAT'L.: SEE NOTES			
				SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1			